



## Description

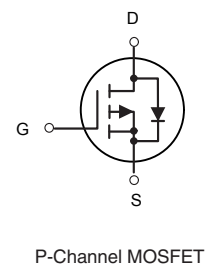
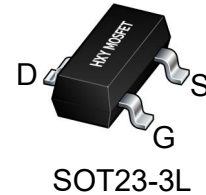
The HXY3407MI uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

## General Features

$V_{DS} = -30V, I_D = -4.1A$   
 $R_{DS(ON)} < 60m\Omega @ V_{GS}=10V$

## Application

High power and current handing capability  
Lead free product is acquired  
Surface mount package  
PWM applications  
Load switch  
Power management



## Package Marking and Ordering Information

| Product ID | Pack     | Marking | Qty(PCS) |
|------------|----------|---------|----------|
| HXY3407MI  | SOT23-3L | A7NV 1B | 3000PCS  |

## Absolute Maximum Ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

| Symbol          | Parameter                                        | Limit      | Unit          |
|-----------------|--------------------------------------------------|------------|---------------|
| $V_{DS}$        | Drain-Source Voltage                             | -30        | V             |
| $V_{GS}$        | Gate-Source Voltage                              | $\pm 20$   | V             |
| $I_D$           | Drain Current-Continuous                         | -4.1       | A             |
| $I_{DM}$        | Drain Current-Pulsed (Note 1)                    | -13        | A             |
| $P_D$           | Maximum Power Dissipation                        | 1.32       | W             |
| $T_J, T_{STG}$  | Operating Junction and Storage Temperature Range | -55 To 150 | $^{\circ}C$   |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 2) | 125        | $^{\circ}C/W$ |



### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

| Symbol                       | Parameter                                      | Conditions                                                   | Min. | Typ.  | Max.      | Unit                |
|------------------------------|------------------------------------------------|--------------------------------------------------------------|------|-------|-----------|---------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=-250\mu A$                                | -30  | ---   | ---       | V                   |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^\circ\text{C}$ , $I_D=-1mA$                 | ---  | -0.02 | ---       | $V/^\circ\text{C}$  |
| $R_{DS(on)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=-10V$ , $I_D=-3A$                                    | ---  | 55    | 60        | $m\Omega$           |
|                              |                                                | $V_{GS}=-4.5V$ , $I_D=-1.5A$                                 | ---  | 90    | 98        |                     |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=-250\mu A$                            | -1.2 | -1.5  | -2.5      | V                   |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |                                                              | ---  | 4.32  | ---       | $mV/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=-24V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$         | ---  | ---   | -1        | $\mu A$             |
|                              |                                                | $V_{DS}=-24V$ , $V_{GS}=0V$ , $T_J=55^\circ\text{C}$         | ---  | ---   | -5        |                     |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                               | ---  | ---   | $\pm 100$ | nA                  |
| $g_{fs}$                     | Forward Transconductance                       | $V_{DS}=-5V$ , $I_D=-3A$                                     | ---  | 4.8   | ---       | S                   |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1MHz$                         | ---  | 24    | 48        | $\Omega$            |
| $Q_g$                        | Total Gate Charge (-4.5V)                      | $V_{DS}=-20V$ , $V_{GS}=-4.5V$ , $I_D=-3A$                   | ---  | 5.22  | 7.3       | nC                  |
| $Q_{gs}$                     | Gate-Source Charge                             |                                                              | ---  | 1.25  | 1.8       |                     |
| $Q_{gd}$                     | Gate-Drain Charge                              |                                                              | ---  | 2.3   | 3.2       |                     |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=-15V$ , $V_{GS}=-10V$ , $R_G=3.3\Omega$<br>$I_D=-1A$ | ---  | 18.4  | 37        | ns                  |
| $T_r$                        | Rise Time                                      |                                                              | ---  | 11.4  | 21        |                     |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |                                                              | ---  | 39.4  | 79        |                     |
| $T_f$                        | Fall Time                                      |                                                              | ---  | 5.2   | 10.4      |                     |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=-15V$ , $V_{GS}=0V$ , $f=1MHz$                       | ---  | 463   | 650       | pF                  |
| $C_{oss}$                    | Output Capacitance                             |                                                              | ---  | 82    | 115       |                     |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |                                                              | ---  | 68    | 95        |                     |

### Diode Characteristics

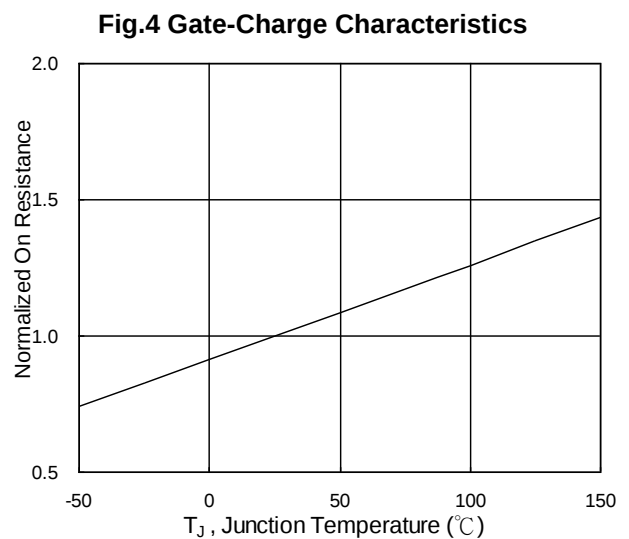
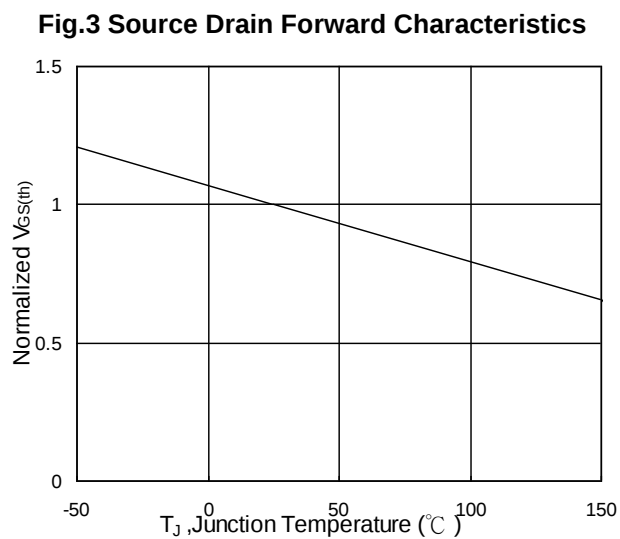
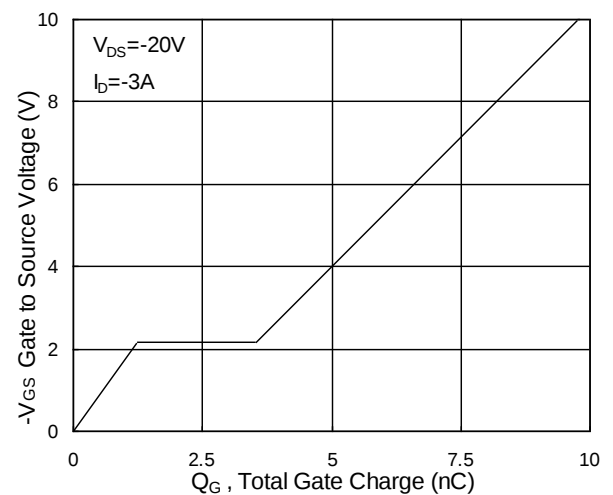
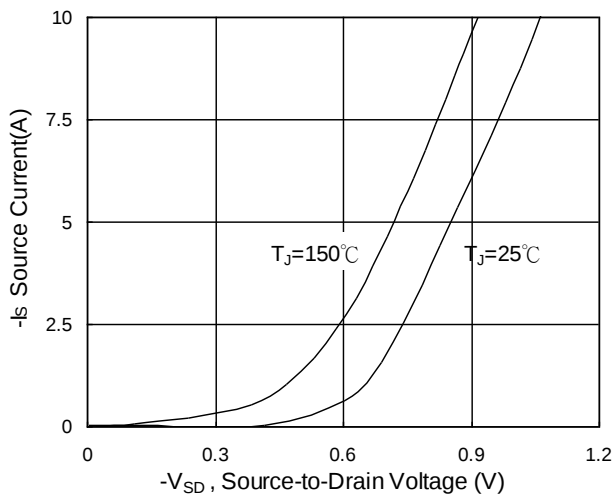
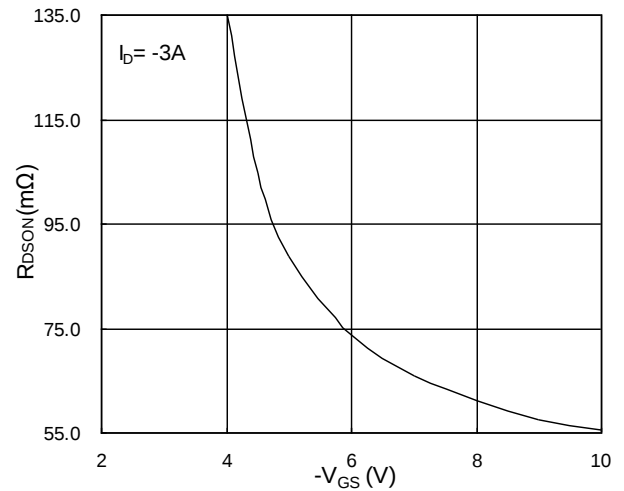
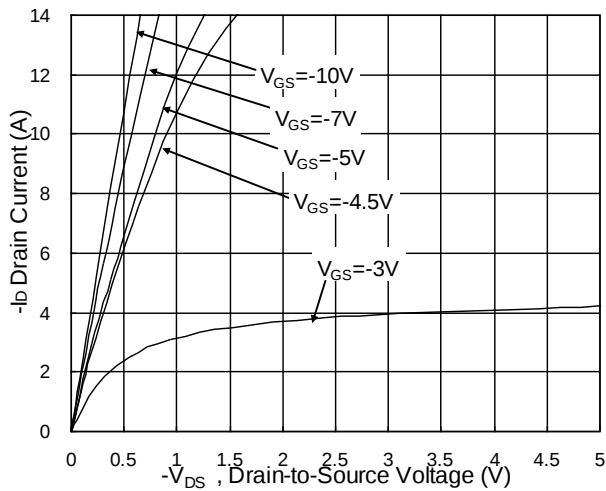
| Symbol   | Parameter                                | Conditions                                       | Min. | Typ. | Max. | Unit |
|----------|------------------------------------------|--------------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,4</sup> | $V_G=V_D=0V$ , Force Current                     | ---  | ---  | -3.2 | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,4</sup>     |                                                  | ---  | ---  | -13  | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=-1A$ , $T_J=25^\circ\text{C}$ | ---  | ---  | -1   | V    |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.



## Typical Characteristics



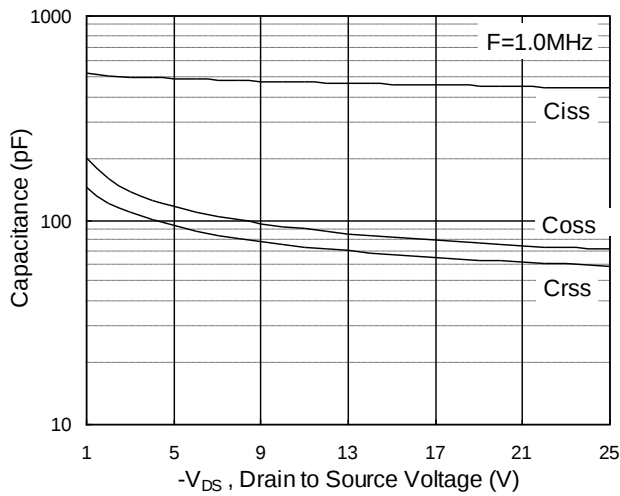


Fig.7 Capacitance

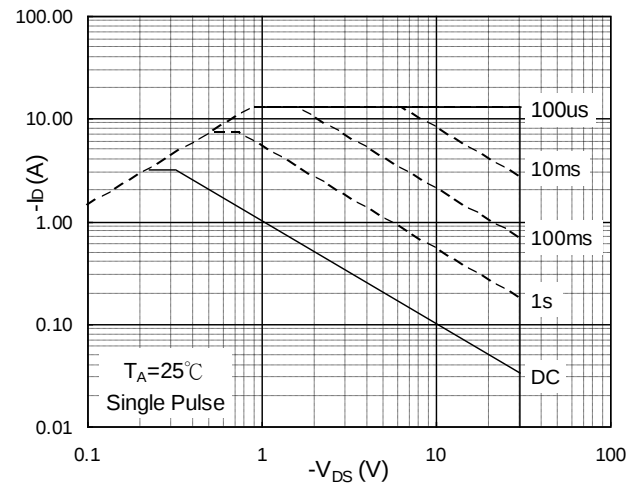


Fig.8 Safe Operating Area

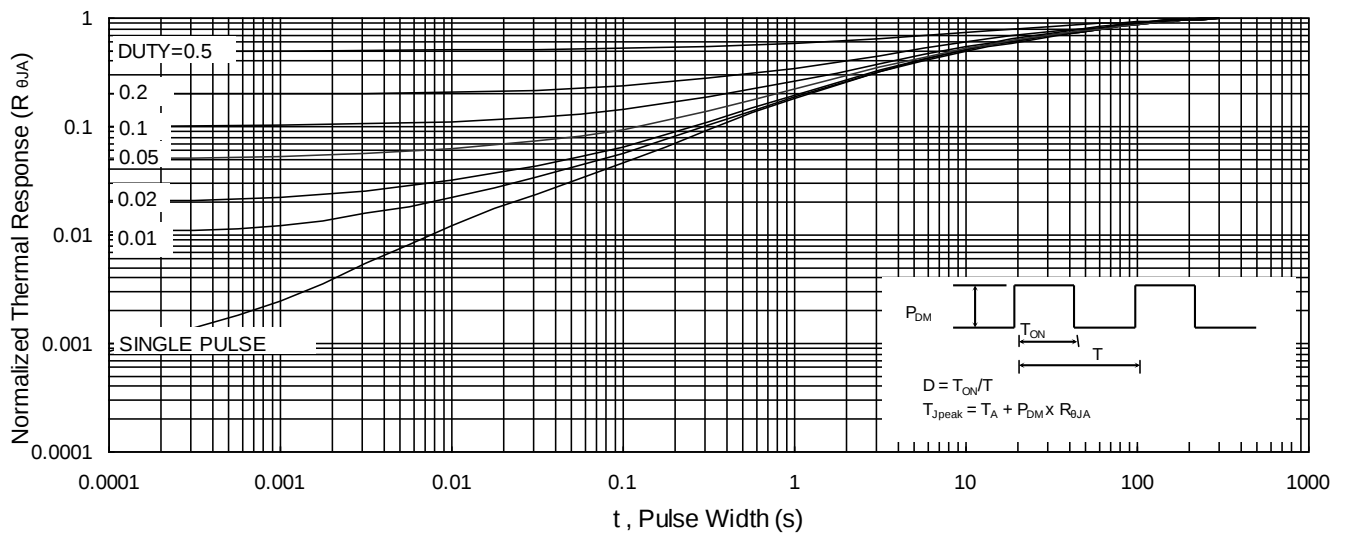


Fig.9 Normalized Maximum Transient Thermal Impedance

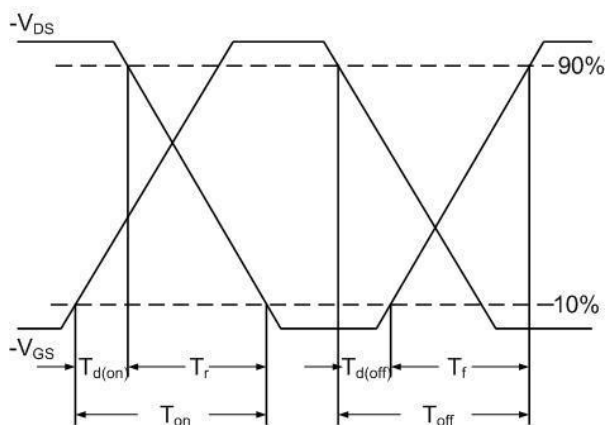


Fig.10 Switching Time Waveform

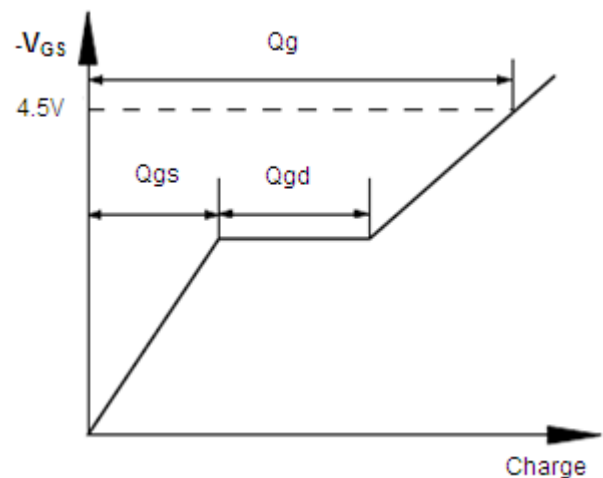
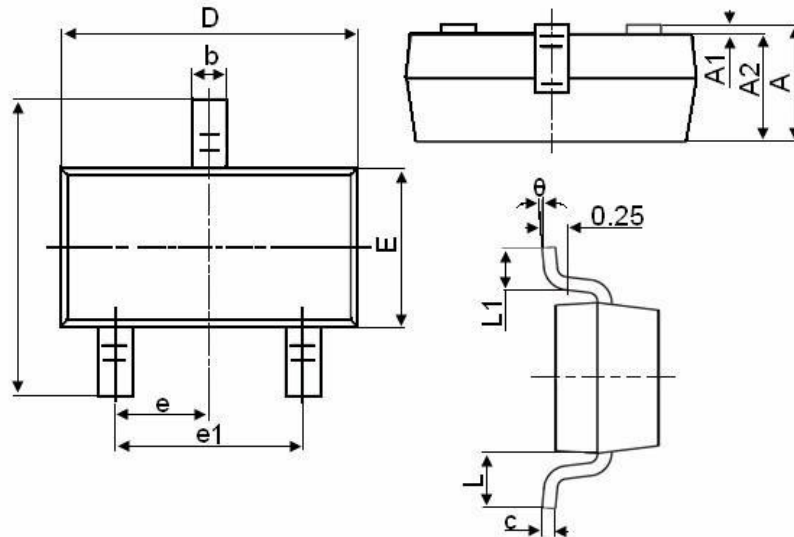


Fig.11 Gate Charge Waveform



## SOT23-3L Package Information



| Symbol | Dimensions in Millimeters |       |
|--------|---------------------------|-------|
|        | MIN.                      | MAX.  |
| A      | 1.050                     | 1.250 |
| A1     | 0.000                     | 0.100 |
| A2     | 1.050                     | 1.150 |
| b      | 0.300                     | 0.500 |
| c      | 0.100                     | 0.200 |
| D      | 2.800                     | 3.000 |
| E      | 1.500                     | 1.700 |
| E1     | 2.650                     | 2.950 |
| e      | 0.950TYP                  |       |
| e1     | 1.800                     | 2.000 |
| L      | 0.550REF                  |       |
| L1     | 0.300                     | 0.600 |
| θ      | 0°                        | 8°    |



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